

Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

Parameter	Rating	Units
V_{DS}	650	V
I_D @ 25°C	38	A
$R_{DS(on)}$	60	m Ω



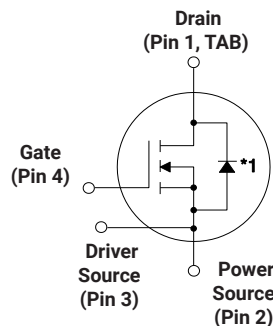
Applications

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating



Inner circuit

TO-247-4
Package



- (1) Drain
- (2) Power Source
- (3) Driver Source
- (4) Gate

*1 Body Diode

Maximum Ratings

Symbol	Parameter	Value	Unit	Note
V_{DSS}	Drain - Source Voltage, $T_C = 25^\circ\text{C}$	650	V	
V_{GS}	Gate - Source voltage (Under transient events < 100 ns)	-8/+19	V	
I_D	Continuous Drain Current, $V_{GS} = 15\text{ V}$, $T_C = 25^\circ\text{C}$	38	A	
	Continuous Drain Current, $V_{GS} = 15\text{ V}$, $T_C = 100^\circ\text{C}$	28		
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width t_p limited by T_{jmax}	99	A	
P_D	Power Dissipation, $T_C=25^\circ\text{C}$, $T_J = 175^\circ\text{C}$	150	W	
T_J, T_{stg}	Operating Junction and Storage Temperature	-40 to +175	$^\circ\text{C}$	
T_L	Solder Temperature, 1.6mm (0.063") from case for 10s	260	$^\circ\text{C}$	
M_d	Mounting Torque, (M3 or 6-32 screw)	1 8.8	Nm lbf-in	

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650			V	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
V_{GSon}	Gate-Source Recommended Turn-On Voltage		15		V	Static	
V_{GSoff}	Gate-Source Recommended Turn-Off Voltage		-4		V		
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.3	3.6	V	$V_{DS} = V_{GS}, I_D = 5\text{ mA}$	
			1.9		V	$V_{DS} = V_{GS}, I_D = 5\text{ mA}, T_J = 175^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current		1	50	μA	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$	
I_{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance	42	60	80	m Ω	$V_{GS} = 15\text{ V}, I_D = 13.2\text{ A}$	
			80			$V_{GS} = 15\text{ V}, I_D = 13.2\text{ A}, T_J = 175^\circ\text{C}$	
g_{fs}	Transconductance		10		S	$V_{DS} = 20\text{ V}, I_{DS} = 13.2\text{ A}$	
			9			$V_{DS} = 20\text{ V}, I_{DS} = 13.2\text{ A}, T_J = 175^\circ\text{C}$	
C_{iss}	Input Capacitance		975		pF	$V_{GS} = 0\text{ V}, V_{DS} = 400\text{ V}$	
C_{oss}	Output Capacitance		80			$f = 1\text{ MHz}$	
C_{rss}	Reverse Transfer Capacitance		9			$V_{AC} = 25\text{ mV}$	
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		99		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 400\text{ V}$	
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		132				
E_{oss}	C_{oss} Stored Energy		15		μJ	$V_{DS} = 600\text{ V}, 1\text{ MHz}$	
E_{ON}	Turn-On Switching Energy (Body Diode)		70		μJ	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V/15 V}, I_D = 13.2\text{ A},$ $R_{G(ext)} = 2.5\Omega, L = 135\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$	
E_{OFF}	Turn Off Switching Energy (Body Diode)		5			FWD = Internal Body Diode of MOSFET	
E_{ON}	Turn-On Switching Energy (External SiC Diode)		64		μJ	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V/15 V}, I_D = 13.2\text{ A},$ $R_{G(ext)} = 2.5\Omega, L = 135\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$	
E_{OFF}	Turn Off Switching Energy (External SiC Diode)		6			FWD = External SiC Diode	
$t_{d(on)}$	Turn-On Delay Time		8		ns	$V_{DD} = 400\text{ V}, V_{GS} = -4\text{ V/15 V}$ $I_D = 13.2\text{ A}, R_{G(ext)} = 2.5\Omega, L = 135\text{ }\mu\text{H}$ Timing relative to V_{DS} Inductive load	
t_r	Rise Time		12				
$t_{d(off)}$	Turn-Off Delay Time		17				
t_f	Fall Time		5				
$R_{G(int)}$	Internal Gate Resistance		3		Ω	$f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$	
Q_{gs}	Gate to Source Charge		13		nC	$V_{DS} = 400\text{ V}, V_{GS} = -4\text{ V/15 V}$ $I_D = 13.2\text{ A}$ Per IEC60747-8-4 pg 21	
Q_{gd}	Gate to Drain Charge		18				
Q_g	Total Gate Charge		44				

Note (1): $C_{o(er)}$, a lumped capacitance that gives same stored energy as C_{oss} while V_{ds} is rising from 0 to 400V $C_{o(tr)}$, a lumped capacitance that gives same charging time as C_{oss} while V_{ds} is rising from 0 to 400V



Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	5.1		V	$V_{GS} = -4\text{ V}, I_{SD} = 6.6\text{ A}, T_J = 25^\circ\text{C}$	
		4.8		V	$V_{GS} = -4\text{ V}, I_{SD} = 6.6\text{ A}, T_J = 175^\circ\text{C}$	
I_S	Continuous Diode Forward Current		23	A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
$I_{S, \text{pulse}}$	Diode pulse Current		99	A	$V_{GS} = -4\text{ V}$, pulse width t_p limited by T_{Jmax}	
t_{rr}	Reverse Recover time	11		ns	$V_{GS} = -4\text{ V}, I_{SD} = 13.2\text{ A}, V_R = 400\text{ V}$ $dif/dt = 4500\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	155		nC		
I_{rrm}	Peak Reverse Recovery Current	27		A		
t_{rr}	Reverse Recover time	16		ns	$V_{GS} = -4\text{ V}, I_{SD} = 13.2\text{ A}, V_R = 400\text{ V}$ $dif/dt = 2400\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	110		nC		
I_{rrm}	Peak Reverse Recovery Current	12		A		

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.99	$^\circ\text{C}/\text{W}$		
$R_{\theta JA}$	Thermal Resistance From Junction to Ambient	40			

Package Dimensions

Unit: mm

